



S3AC THRU S3MC

3.0 AMP SURFACE MOUNT SILICON RECTIFIERS



FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.21 grams

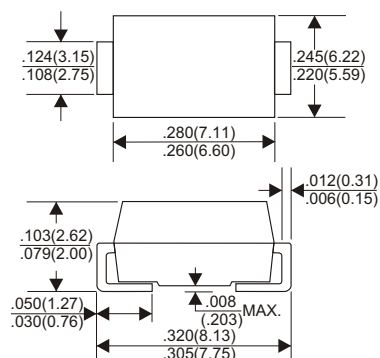
VOLTAGE RANGE

50 to 1000 Volts

CURRENT

3.0 Ampere

DO-214AB(SMC)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	S3AC	S3BC	S3DC	S3GC	S3JC	S3KC	S3MC	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current At T _L =100°C	3.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	100							A
Maximum Instantaneous Forward Voltage at 3.0A	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage Ta=25°C	5.0							μA
Typical Junction Capacitance (Note1)	60							pF
Typical Thermal Resistance R _{JL} (Note 2)	13							°C/W
Operating and Storage Temperature Range T _J , T _{stg}	-55 — +150							°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES (S3AC THRU S3MC)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

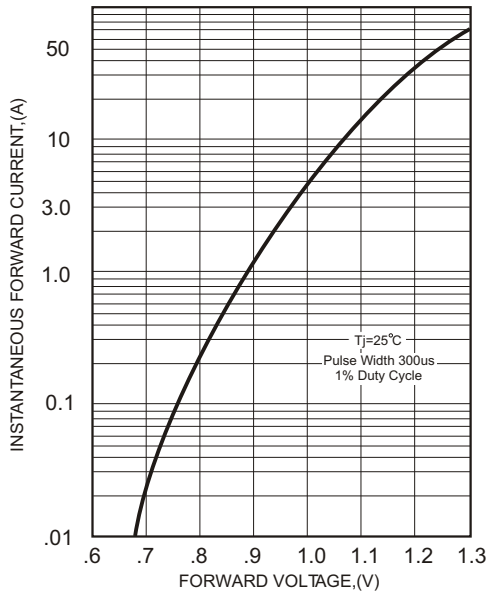


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

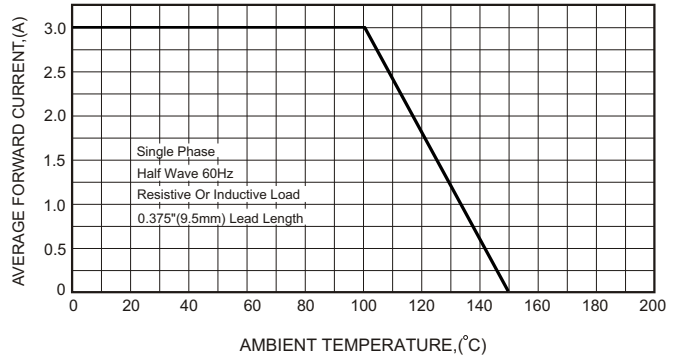


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

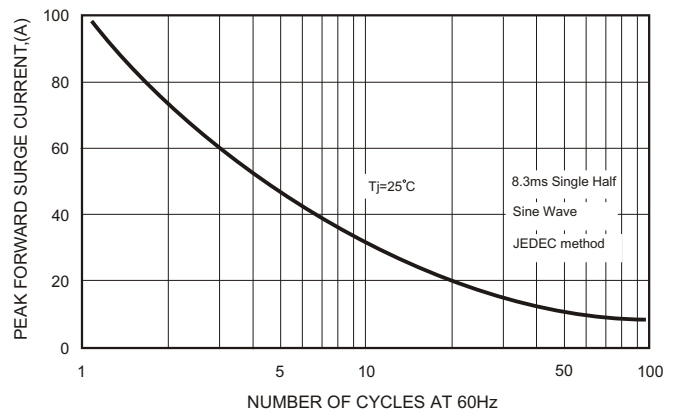


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

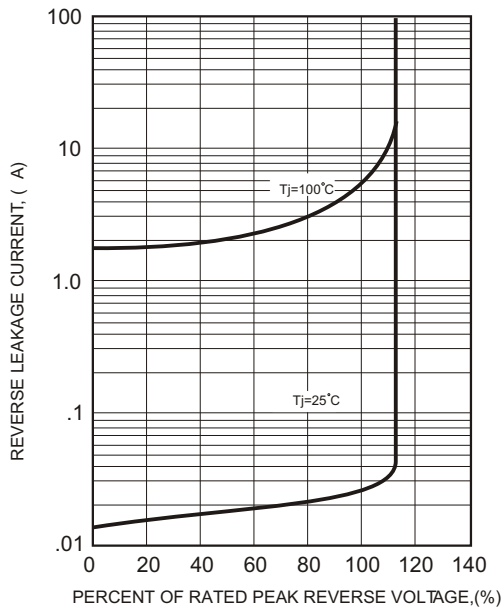
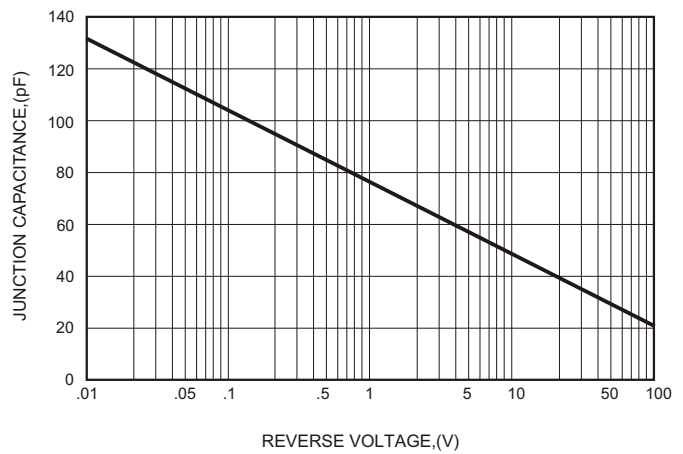


FIG.5-TYPICAL JUNCTION CAPACITANCE



Attention:

The graph is for reference only, can't be the basis for judgment.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement.